

WHAT IS CLAIMED IS:

1. A display comprising: a scan line for driving pixels formed on an insulating substrate; a signal line which crosses the scan line; and
5 a driving circuit connected to the signal line and, in a region other than a display region constructed by the pixels, directly mounted on the insulating substrate, wherein a warp amount of a portion corresponding to the region in which the driving circuit is mounted, in a face opposite to the side of the insulating substrate, on which the driving circuit is
10 mounted, is 2 μm or less.

2. The display of Claim 1, wherein the driving circuit and a terminal on the insulating substrate are connected to each other by an anisotropic conductive film.

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3. A method of manufacturing a display comprising a scan line for driving pixels formed on an insulating substrate; a signal line which crosses the scan line; a driving circuit connected to the signal line and, in a region other than a display region constructed by the pixels,
20 directly mounted on a terminal on the insulating substrate; and a stage disposed on the face of the insulating substrate, the driving circuit being not mounted on the face, wherein the method comprises a step of connecting the terminal on the insulating substrate and the driving circuit by using an anisotropic conductive film in a state where a
25 temperature of a face, which is in contact with the insulating substrate, of the stage is equal to or higher than a temperature of the anisotropic conductive film under the driving circuit.

4. A method of manufacturing a display comprising a scan line for driving pixels formed on an insulating substrate; a signal line which crosses the scan line; a driving circuit connected to the signal line and, in a region other than a display region constructed by the pixels,
5 directly mounted on a terminal on the insulating substrate; a stage disposed on the face of the insulating substrate, the driving circuit being not mounted on the face; and a compression bonding part disposed on the face opposite to a connection terminal in the driving circuit connected to the terminal on the insulating substrate, wherein the
10 method comprises a step of connecting the terminal on the insulating substrate and the driving circuit by using an anisotropic conductive film in a state where a temperature of a face, which is in contact with the insulating substrate of the stage is higher than a temperature of the face, which is in contact with the driving circuit, of the compression bonding
15 part.

5. The method of manufacturing a display of any one of Claims 3 to 4, wherein the temperature of the face of the stage in contact with the insulating substrate is 150 to 220°C.

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6. The method of manufacturing a display of any one of Claims 3 to 5, wherein the method further includes a step of controlling the temperature of the face, which is in contact with the insulating substrate, of the stage when the terminal on the insulating substrate
25 and the driving circuit are connected by using an anisotropic conductive film.

7. The method of manufacturing a display any one of Claims 3 to 6, wherein the method further includes a step of cooling the face, which is in contact with the insulating substrate, of the stage after connection of the terminal on the insulating substrate and the driving
5 circuit.

8. An apparatus for manufacturing a display comprising a scan line for driving pixels formed on an insulating substrate; a signal line which crosses the scan line; a driving circuit connected to the signal
10 line and, in a region other than a display region constructed by the pixels, directly mounted on a terminal on the insulating substrate; a stage disposed on the face of the insulating substrate on which the driving circuit is not mounted; and a compression bonding part disposed on the face opposite to a connection terminal in the driving circuit
15 connected to the terminal on the insulating substrate, wherein the terminal on the insulating substrate and the driving circuit are connected to each other in a state where a temperature of a face, which is in contact with the insulating substrate, of the stage is higher than a temperature of the face, which is in contact with the driving circuit, of
20 the compression bonding part.